



Hysol[®] US5538

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PRODUCT DESCRIPTION

Hysol[®] US5538 is a flexible, unfilled, potting compound. This system provides low viscosity for good flow and good adhesion to many substrates. It is a low odor system designed to be friendly in the work environment. This material can be used to encapsulate load coils, transformers, etc. Sand can be added as an extender that increases thermal conductivity and decreases shrinkage and cost.

APPLICATION CHARACTERISTICS

Viscosity, cps @ 25°C	UA5538	55
	UB5538	850
	Mixed	450
Specific Gravity @ 25°C	UA5538	1.24
	UB5538	0.96
	Mixed	1.06
Working Time, 105 gm mass, minutes		20-40
Gel Time, 105 gm mass, minutes		45-75
Recommended Cure Cycle, hours		
	Normal @ 25°C	24-48
	Alternate @ 60-85°C	1-3
Color		Black
Mix Ratio, UA5538/UB5538	By weight	30/70
	By Volume	1/3.01
Shelf Life in unopened containers, months		12

TYPICAL CURED PROPERTIES

Hardness, Shore A	65
Coefficient of Thermal Conductivity, W/mK	0.180
Weight Loss, 168 hrs. @ 125°C, %	0.005
Glass Transition Temperature, °C	-12

TYPICAL ELECTRICAL PROPERTIES

Dielectric Constant @ 25°C		
	100 kHz	3.2
Dissipation Factor @ 25°C		
	100 kHz	0.05
Dielectric Strength, volts/mil		955
Surface Resistivity, ohms @ 25°C, x 10 ¹³		3.1
Volume Resistivity, ohm-cm, x 10 ¹⁵		1.6

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

STORAGE

Liquid Storage – Liquids should be stored at 23°C or below, in closed containers. If stored below 23°C, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination.

DATA RANGES

The data contained herein may be reported as a typical value and/or range values based on actual test data and are verified on a periodic basis.

Note

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